

# Call for Papers

## IEEE Asian Solid-State Circuits Conference

### A-SSCC 2024



**Location: International Conference Center Hiroshima, Japan**

**Date: November 18 – 21, 2024**

Sponsored by IEEE SSCS, IEEE Region-10 SSCS Chapters

<https://a-sscc2024.org/>

<https://sscs.ieee.org/>

The IEEE A-SSCC 2024 (Asian Solid-State Circuits Conference) is an international forum for presenting the most updated and advanced chips and circuit designs in solid-state and semiconductor fields. The conference is supported by the IEEE Solid-State Circuits Society and will be held in Asia. Further details on the conference and paper submission guidelines and templates will be available at the A-SSCC official website <http://www.asscc.org/> (or <https://www.a-sscc2024.org/>).

#### Paper Submission

Prospective authors are invited to submit **two-page** manuscripts, including figures, tables and references, to the official A-SSCC 2024 website. **The two-page submission could include one-page additional supplements with figures and figure captions. Supplementary figures should not be referred to in the text of the paper.** For further details, see the A-SSCC Website. Papers are solicited in the following categories:

#### Regular Session

- Analog Circuits & Systems:** Amplifiers, comparators, switched capacitor circuits, continuous-time & discrete-time filters, voltage/current references; DC-DC converters, power-control circuits; IF/baseband analog circuits, AGC/VGA; non-linear analog circuits.
- Data Converters:** Nyquist-rate and oversampling A/D, D/A converters, time-to-digital converters, and capacitance-to-digital converters; sub-circuits for data converters including sample-and-hold circuits, calibration circuits, etc.
- Digital Circuits & Systems:** Design, fabrication, and test of digital VLSI systems; high-speed low-power digital circuits, power-reduction and management methods for digital VLSI, ultra-low-voltage and sub-threshold logic design; leakage reduction techniques; clock distribution, I/O circuits, reconfigurable logic-array circuits; supply/substrate noise measurement and cancellation for digital VLSI, variation and fault-tolerant circuits.
- SoC & Signal Processing Systems:** System-on-chip (including 3D integration), microprocessors, network processors, baseband communication processing system & architectures, system-level power management; multimedia and recognition processing systems; cryptographic, security, machine learning, deep-learning, and neuromorphic circuits and systems; bio-medical/neural-network processors and sensor network systems.
- Wireless:** Receivers/transmitters/transceivers for wireless systems; narrowband RF, ultra-wideband and millimeter-wave circuits; circuits and building-blocks including RF front-end, LNA, mixer, power amplifiers, VCOs, frequency synthesizers, RF filters, RF switches, power detectors, active antennas.
- Wireline:** Receivers/transmitters/transceivers for wireline systems; optical/electrical data links and backplane transceivers; power-line communication; clock generation circuits, PLL, DLL, spread-spectrum clock generation; building blocks for high-speed wireline communication; analog-digital mixed-mode circuits.
- Emerging Technologies and Applications:** Advanced system designs and circuit solutions for technologies and applications including state-of-the-art devices and packaging technologies; flexible and printable electronics; silicon photonics; smart sensors and transducers; MEMS for analog, RF, and sensor applications; image sensors and displays; energy harvesting systems; transceiver systems; medical/bio-electronics/bio-inspired chip design, artificial intelligent system, and cryogenic circuits and systems.
- Memory:** Volatile and Non-volatile memory; new memory designs for 3D/2D architectures, emerging devices such as resistive-/phase change-/magnetic-/ferro-electric- memory devices; data storage and multi-bit-cell memory design; cache-memory system, multi-port memory, memory subsystem, processing in memory, and CAM design; yield-enhancing and ECC techniques; memory testing and built-in self-test.
- FPGA:** Novel algorithm and/or architecture for integrated circuits validated by FPGA implementation. The authors of accepted papers are required to participate in demo sessions.

#### Special Session

- Industry Program:** This special category accepts only papers based on state-of-the-art industrial products. Strong emphasis on systems realized by silicon chips is encouraged. The papers should cover architecture, circuits, process technology, packaging and testing, including characterization results, die and system photos, as well as product demos.
- Demonstration Program:** Three demonstration sessions will be held during the Conference. Student Design Contest (SDC) and FPGA Demo will be presented by the authors of selected papers, and Industry Demo including Strat-up Showcase will be offered by industry groups who voluntarily apply for participation without paper submission.
- Special Program:** Diverse special programs including Educational Session, Panels, and Mini-Forums will be organized. In addition, other exciting joint programs such as ESSCIRC CICC Joint Session, Young Professionals and Women-in-Circuits (WiC) Joint Mentoring Session, Start-ups Forum, and IT Vision in Asia will be held during the Conference.

Papers related to integrated circuits for intelligent systems are highly solicited. Papers on low-power and/or low-voltage approaches, signal integrity, noise, test, and manufacturability for all the above categories are welcomed. Measurement results are highly recommended, especially for analog, and RF categories. Design methodologies for SiP, and SoC are included in the scope of the conference the papers only describing CAD tools and CAD algorithms are not considered. Authors must follow detailed instruction provided within the "Authors" section of the website, including the Authors' Guide and Pre-Publication Policy. The technical content beyond the abstract of the accepted paper must not be announced, published, or in any way put in the public domain prior to the Conference. Extended versions of selected papers from the Conference will be published in a Special Issue of the IEEE Journal of Solid-State Circuits and a Special Issue of the IEEE Solid-State Circuits Letters.

#### Important dates

**Extended paper submission**  
**Final paper submission**

**June 24, 2024, 20:00 (GMT)**  
**September 12, 2024**

**Acceptance notification**

**August 9, 2024**

Steering Committee	Chair	Hoi-Jun YOO, <i>KAIST, Korea</i>	hjyoo [at] kaist.ac.kr
Organizing Committee	Conference Chair	Hideshi MIYAJIMA, <i>Kioxia, Japan</i>	hideshi.miyajima [at] kioxia.com
	Organizing Committee Co-Chair	Ryuichi FUJIMOTO, <i>Kioxia, Japan</i> Sugako OTANI, <i>Renesas Electronics, Japan</i>	ryuichi.fujimoto [at] kioxia.com sugako.otani.uj [at] renesas.com
Technical Program Committee	Chair	Pei-Yun TSAI, <i>National Central University, Taiwan</i>	pytsai [at] ee.ncu.edu.tw
	Co-Chair	Baoyong CHI, <i>Tsinghua University, China</i>	chibylxc [at] tsinghua.edu.cn
	Vice-Chair	Tsung-Heng TSAI, <i>National Yang-Ming Chiao-Tung University, Taiwan</i>	henrytsai [at] nycu.edu.tw